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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	19700
Total RAM Bits	434176
Number of I/O	360
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	484-BBGA
Supplier Device Package	484-FPBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfec20e-4fn484i

Features

■ Extensive Density and Package Options

- 1.5K to 32.8K LUT4s
- 65 to 496 I/Os
- Density migration supported

■ sysDSP™ Block (LatticeECP™ Versions)

- High performance multiply and accumulate
- 4 to 8 blocks
 - 4 to 8 36x36 multipliers or
 - 16 to 32 18x18 multipliers or
 - 32 to 64 9x9 multipliers

■ Embedded and Distributed Memory

- 18 Kbits to 498 Kbits sysMEM™ Embedded Block RAM (EBR)
- Up to 131 Kbits distributed RAM
- Flexible memory resources:
 - Distributed and block memory

■ Flexible I/O Buffer

- Programmable sysI/O™ buffer supports wide range of interfaces:

- LVCMOS 3.3/2.5/1.8/1.5/1.2
- LVTTTL
- SSTL 3/2 Class I, II, SSTL18 Class I
- HSTL 18 Class I, II, III, HSTL15 Class I, III
- PCI
- LVDS, Bus-LVDS, LVPECL, RSDS

■ Dedicated DDR Memory Support

- Implements interface up to DDR400 (200MHz)

■ sysCLOCK™ PLLs

- Up to four analog PLLs per device
- Clock multiply, divide and phase shifting

■ System Level Support

- IEEE Standard 1149.1 Boundary Scan, plus ispTRACY™ internal logic analyzer capability
- SPI boot flash interface
- 1.2V power supply

■ Low Cost FPGA

- Features optimized for mainstream applications
- Low cost TQFP and PQFP packaging

Table 1-1. LatticeECP/EC Family Selection Guide

Device	LFEC1	LFEC3	LFEC6/ LFCEP6	LFEC10/ LFCEP10	LFEC15/ LFCEP15	LFEC20/ LFCEP20	LFEC33/ LFCEP33
PFU/PFF Rows	12	16	24	32	40	44	64
PFU/PFF Columns	16	24	32	40	48	56	64
PFUs/PFFs	192	384	768	1280	1920	2464	4096
LUTs (K)	1.5	3.1	6.1	10.2	15.4	19.7	32.8
Distributed RAM (Kbits)	6	12	25	41	61	79	131
EBR SRAM (Kbits)	18	55	92	276	350	424	498
EBR SRAM Blocks	2	6	10	30	38	46	54
sysDSP Blocks ¹	—	—	4	5	6	7	8
18x18 Multipliers ¹	—	—	16	20	24	28	32
V _{CC} Voltage (V)	1.2	1.2	1.2	1.2	1.2	1.2	1.2
Number of PLLs	2	2	2	4	4	4	4
Packages and I/O Combinations:							
100-pin TQFP (14 x 14 mm)	67	67					
144-pin TQFP (20 x 20 mm)	97	97	97				
208-pin PQFP (28 x 28 mm)	112	145	147	147			
256-ball fpBGA (17 x 17 mm)		160	195	195	195		
484-ball fpBGA (23 x 23 mm)			224	288	352	360	360
672-ball fpBGA (27 x 27 mm)						400	496

1. LatticeECP devices only.

Secondary Clock Sources

LatticeECP/EC devices have four secondary clock resources per quadrant. The secondary clock branches are tapped at every PFU. These secondary clock networks can also be used for controls and high fanout data. These secondary clocks are derived from four clock input pads and 16 routing signals as shown in Figure 2-7.

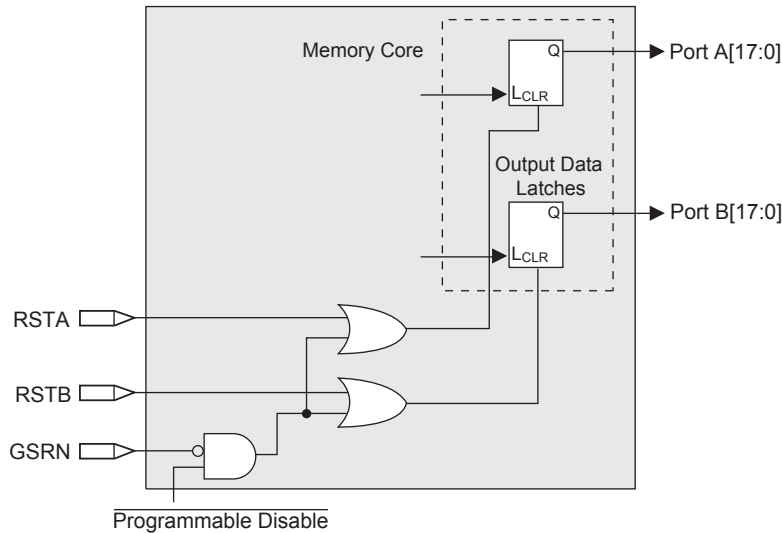
Figure 2-7. Secondary Clock Sources



Clock Routing

The clock routing structure in LatticeECP/EC devices consists of four Primary Clock lines and a Secondary Clock network per quadrant. The primary clocks are generated from MUXs located in each quadrant. Figure 2-8 shows this clock routing. The four secondary clocks are generated from MUXs located in each quadrant as shown in Figure 2-9. Each slice derives its clock from the primary clock lines, secondary clock lines and routing as shown in Figure 2-10.

Figure 2-16. Memory Core Reset

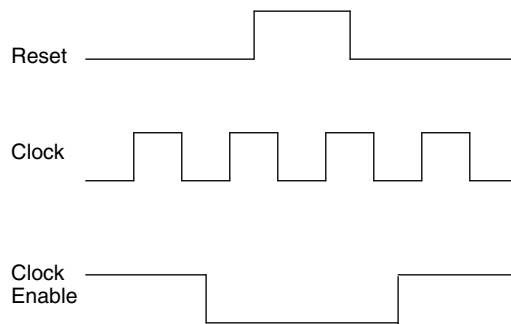


For further information about sysMEM EBR block, please see the the list of technical documentation at the end of this data sheet.

EBR Asynchronous Reset

EBR asynchronous reset or GSR (if used) can only be applied if all clock enables are low for a clock cycle before the reset is applied and released a clock cycle after the reset is released, as shown in Figure 2-17. The GSR input to the EBR is always asynchronous.

Figure 2-17. EBR Asynchronous Reset (Including GSR) Timing Diagram



If all clock enables remain enabled, the EBR asynchronous reset or GSR may only be applied and released after the EBR read and write clock inputs are in a steady state condition for a minimum of $1/f_{MAX}$ (EBR clock). The reset release must adhere to the EBR synchronous reset setup time before the next active read or write clock edge.

If an EBR is pre-loaded during configuration, the GSR input must be disabled or the release of the GSR during device Wake Up must occur before the release of the device I/Os becomes active.

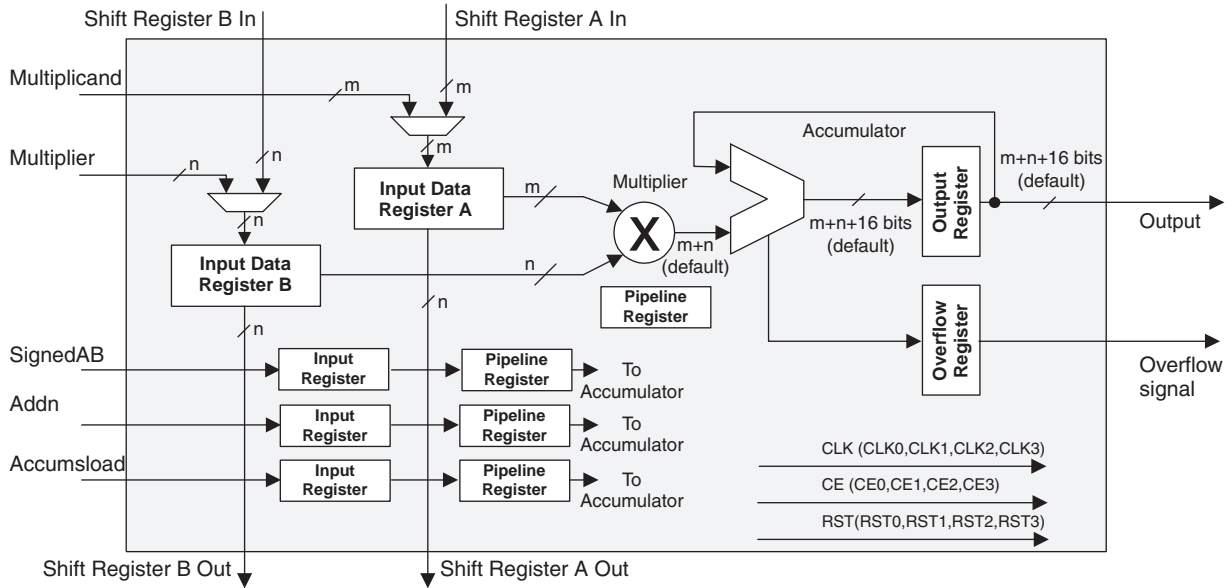
These instructions apply to all EBR RAM and ROM implementations.

Note that there are no reset restrictions if the EBR synchronous reset is used and the EBR GSR input is disabled.

sysDSP Block

The LatticeECP-DSP family provides a sysDSP block, making it ideally suited for low cost, high performance Digital Signal Processing (DSP) applications. Typical functions used in these applications are Finite Impulse Response (FIR) filters; Fast Fourier Transforms (FFT) functions, correlators, Reed-Solomon/Turbo/Convolution encoders and

Figure 2-20. MAC sysDSP Element



MULTADD sysDSP Element

In this case, the operands A0 and B0 are multiplied and the result is added/subtracted with the result of the multiplier operation of operands A1 and B1. The user can enable the input, output and pipeline registers. Figure 2-21 shows the MULTADD sysDSP element.

Figure 2-21. MULTADD

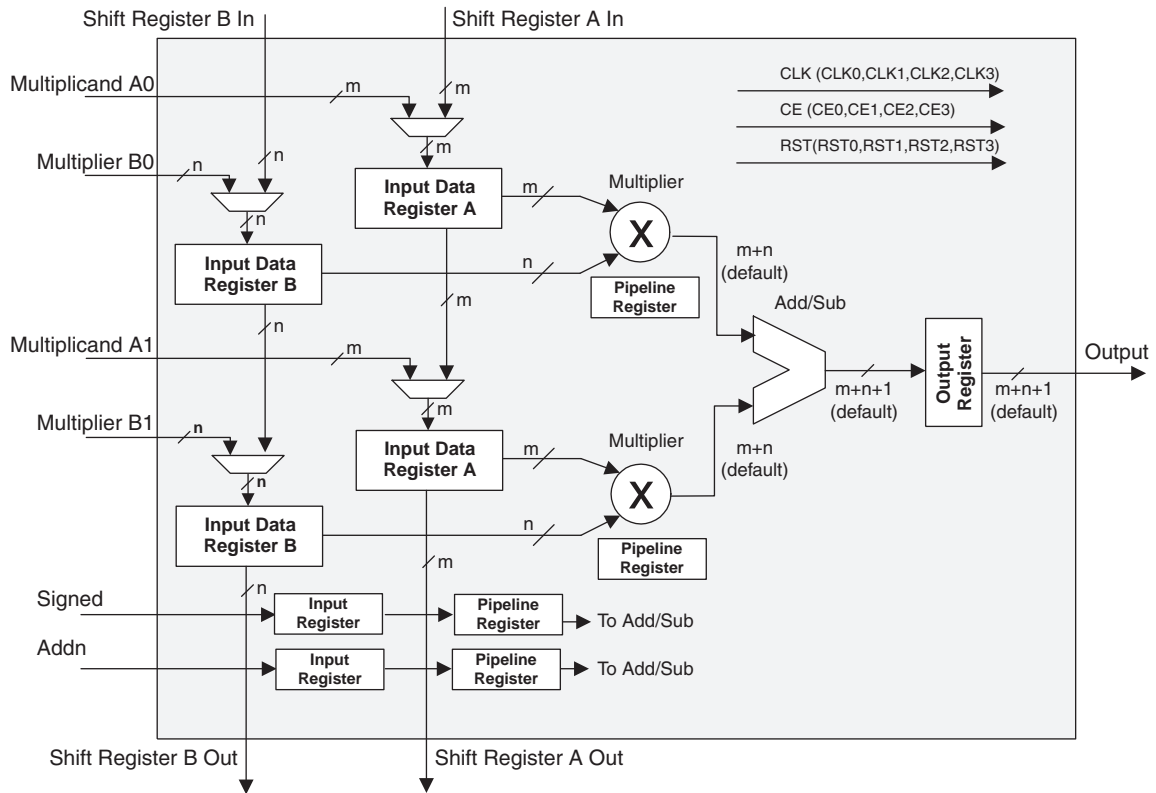
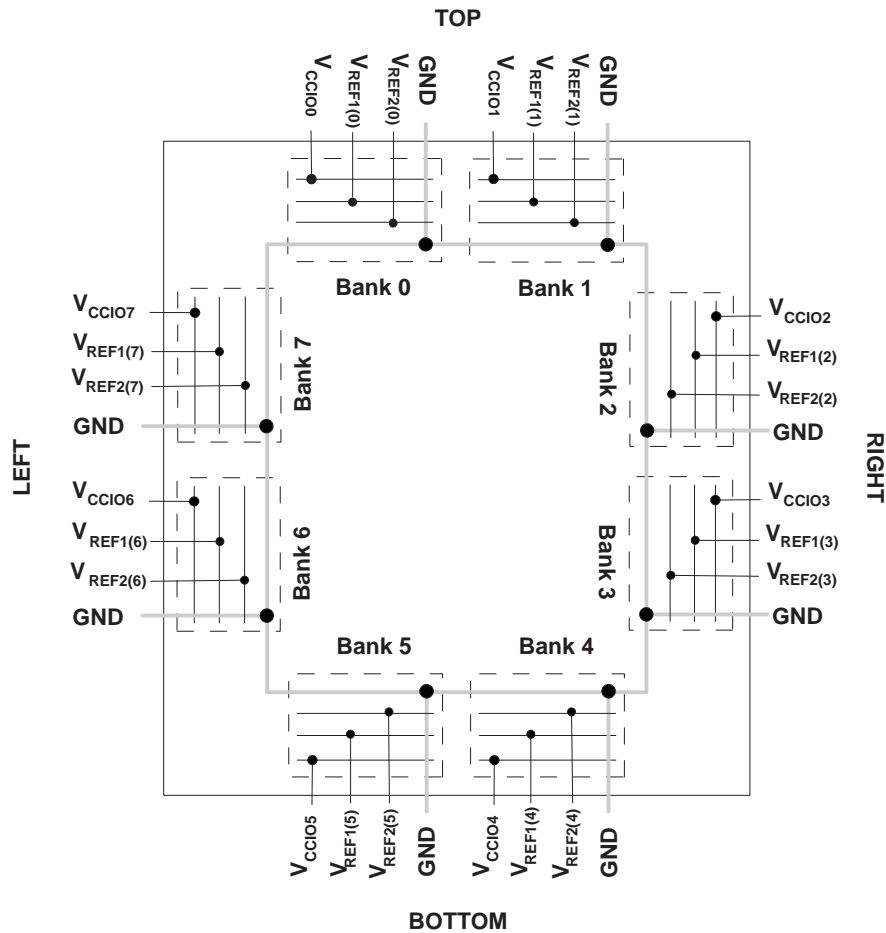


Figure 2-34. LatticeECP/EC Banks



LatticeECP/EC devices contain two types of sysI/O buffer pairs.

1. **Top and Bottom sysI/O Buffer Pairs (Single-Ended Outputs Only)**

The sysI/O buffer pairs in the top and bottom banks of the device consist of two single-ended output drivers and two sets of single-ended input buffers (both ratioed and referenced). The referenced input buffer can also be configured as a differential input.

The two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential input buffer and the comp (complementary) pad is associated with the negative side of the differential input buffer.

Only the I/Os on the top and bottom banks have programmable PCI clamps. These I/O banks also support hot socketing with I_{DK} less than 1mA. Note that the PCI clamp is enabled after V_{CC}, V_{CCAUX} and V_{CCIO} are at valid operating levels and the device has been configured.

2. **Left and Right sysI/O Buffer Pairs (Differential and Single-Ended Outputs)**

The sysI/O buffer pairs in the left and right banks of the device consist of two single-ended output drivers, two sets of single-ended input buffers (both ratioed and referenced) and one differential output driver. The referenced input buffer can also be configured as a differential input. In these banks the two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential I/O, and the comp (complementary) pad is associated with the negative side of the differential I/O.

Only the left and right banks have LVDS differential output drivers. See the I_{DK} specification for I/O leakage current during power-up.

Derating Timing Tables

Logic Timing provided in the following sections of the data sheet and the ispLEVER design tools are worst-case numbers in the operating range. Actual delays at nominal temperature and voltage for best-case process, can be much better than the values given in the tables. To calculate logic timing numbers at a particular temperature and voltage multiply the noted numbers with the derating factors provided below.

The junction temperature for the FPGA depends on the power dissipation by the device, the package thermal characteristics (Θ_{JA}), and the ambient temperature, as calculated with the following equation:

$$T_{JMAX} = T_{AMAX} + (\text{Power} * \Theta_{JA})$$

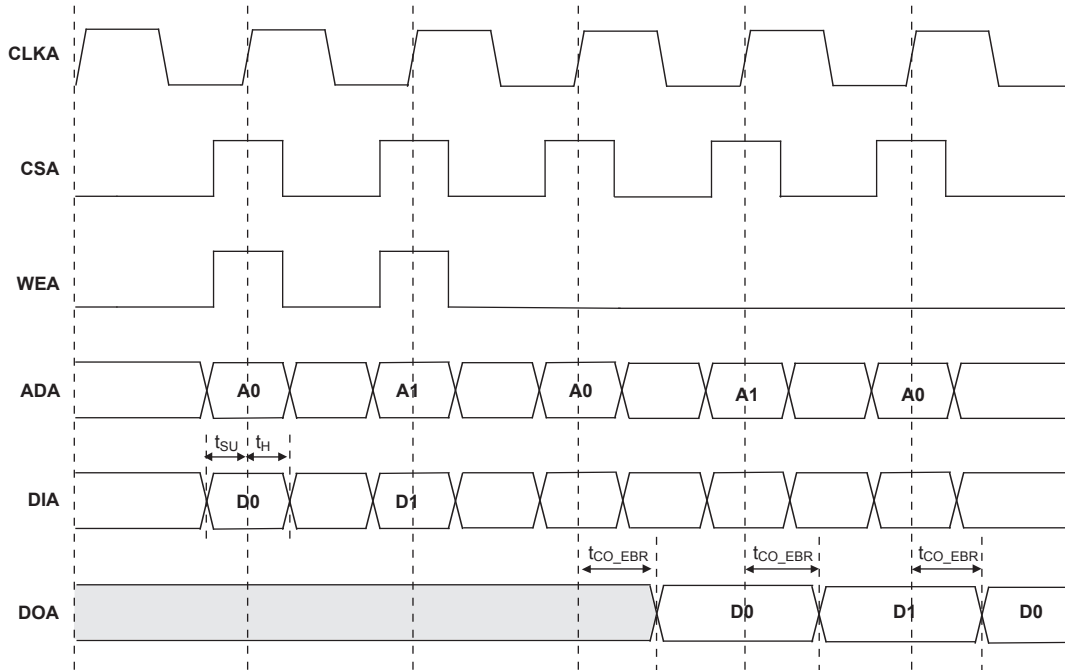
The user must determine this temperature and then use it to determine the derating factor based on the following derating tables: T_J °C.

Table 3-5. Delay Derating Table for Internal Blocks

T_J °C Commercial	T_J °C Industrial	Power Supply Voltage		
		1.14V	1.2V	1.26V
—	-40	0.82	0.77	0.71
—	-25	0.82	0.76	0.71
0	20	0.89	0.83	0.78
25	45	0.93	0.87	0.81
85	105	1.00	0.94	0.89

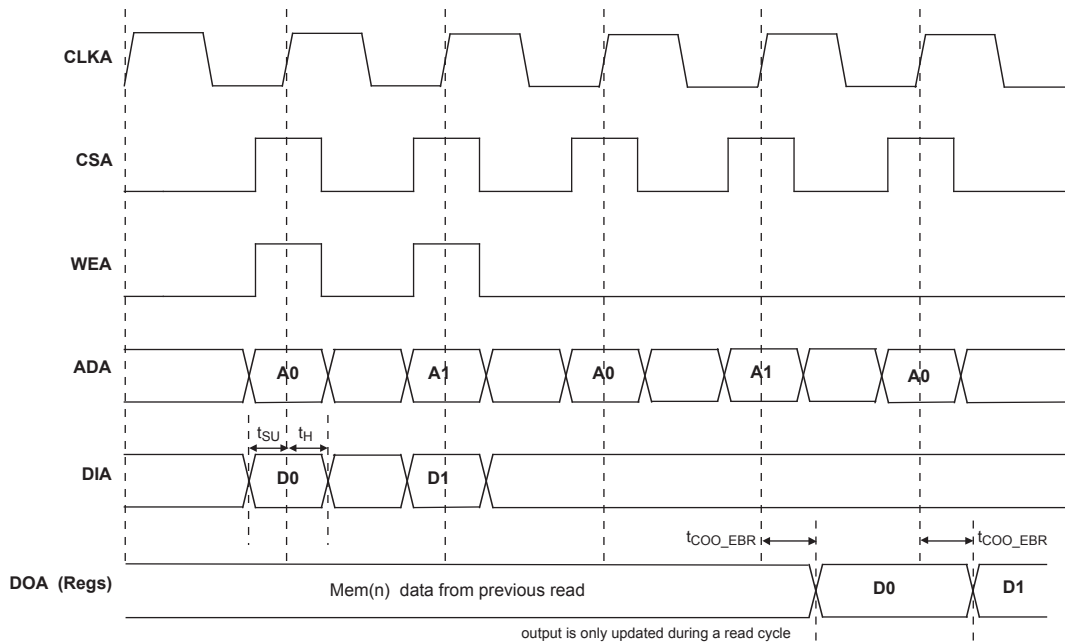
EBR Memory Timing Diagrams

Figure 3-8. Read/Write Mode (Normal)



Note: Input data and address are registered at the positive edge of the clock and output data appears after the positive edge of the clock.

Figure 3-9. Read/Write Mode with Input and Output Registers

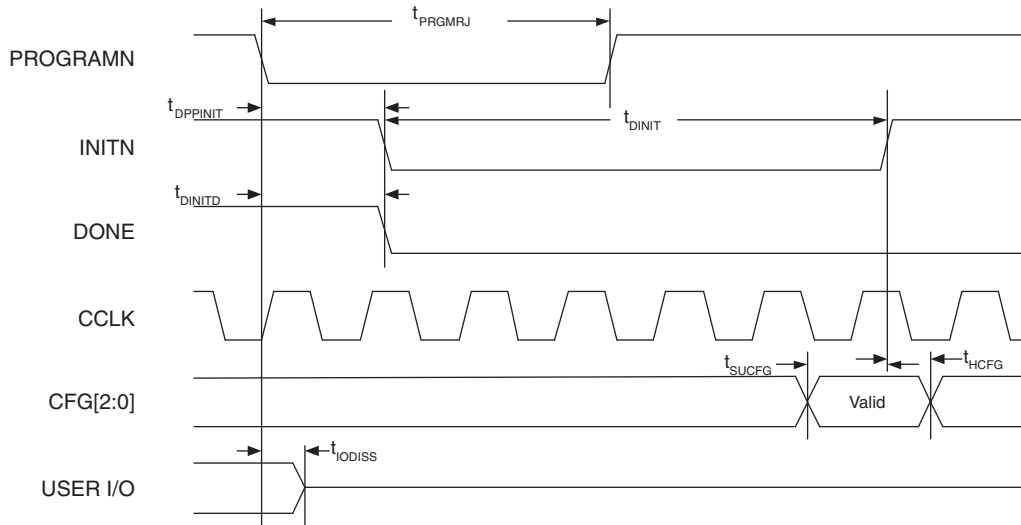


LatticeECP/EC sysCONFIG Port Timing Specifications

Over Recommended Operating Conditions

Parameter	Description	Min.	Typ.	Max.	Units
sysCONFIG Byte Data Flow					
t _{SUCBDI}	Byte D[0:7] Setup Time to CCLK	7		—	ns
t _{HCBDI}	Byte D[0:7] Hold Time to CCLK	1		—	ns
t _{CODO}	Clock to Dout in Flowthrough Mode	—		12	ns
t _{SUCS}	CS[0:1] Setup Time to CCLK	7		—	ns
t _{HCS}	CS[0:1] Hold Time to CCLK	1		—	ns
t _{SUWD}	Write Signal Setup Time to CCLK	7		—	ns
t _{HWD}	Write Signal Hold Time to CCLK	1		—	ns
t _{DCB}	CCLK to BUSY Delay Time	—		12	ns
t _{CORD}	Clock to Out for Read Data	—		12	ns
sysCONFIG Byte Slave Clocking					
t _{BSCH}	Byte Slave Clock Minimum High Pulse	6		—	ns
t _{BSCL}	Byte Slave Clock Minimum Low Pulse	9		—	ns
t _{BSCYC}	Byte Slave Clock Cycle Time	15		—	ns
t _{SUSCDI}	Din Setup time to CCLK Slave Mode	7		—	ns
t _{HSCDI}	Din Hold Time to CCLK Slave Mode	1		—	ns
t _{CODO}	Clock to Dout in Flowthrough Mode	—		12	ns
sysCONFIG Serial (Bit) Data Flow					
t _{SUMCDI}	Din Setup time to CCLK Master Mode	7		—	ns
t _{HMCDI}	Din Hold Time to CCLK Master Mode	1		—	ns
sysCONFIG Serial Slave Clocking					
t _{SSCH}	Serial Slave Clock Minimum High Pulse	6		—	ns
t _{SSCL}	Serial Slave Clock Minimum Low Pulse	6		—	ns
sysCONFIG POR, Initialization and Wake Up					
t _{ICFG}	Minimum Vcc to INIT High	—		50	ms
t _{VMC}	Time from t _{ICFG} to Valid Master Clock	—		2	us
t _{PRGMRJ}	Program Pin Pulse Rejection	—		8	ns
t _{PRGM}	PROGRAMN Low Time to Start Configuration	25		—	ns
t _{DINIT}	INIT Low Time	—		1	ms
t _{DPPINIT}	Delay Time from PROGRAMN Low to INIT Low	—		37	ns
t _{DINITD}	Delay Time from PROGRAMN Low to DONE Low	—		37	ns
t _{IODISS}	User I/O Disable from PROGRAMN Low	—		35	ns
t _{IOENSS}	User I/O Enabled Time from CCLK Edge During Wake Up Sequence	—		25	ns
t _{MWC}	Additional Wake Master Clock Signals after Done Pin High	120		—	cycles
t _{SUCFG}	CFG to INITN Setup Time	100		—	ns
t _{HCFG}	CFG to INITN Hold Time	100		—	ns
sysCONFIG SPI Port					
t _{CFGX}	Init High to CCLK Low	—		80	ns
t _{CSSPI}	Init High to CSSPIN Low	—		2	us
t _{CSCCLK}	CCLK Low Before CSSPIN Low	0		-	ns
t _{SOCDO}	CCLK Low to Output Valid	—		15	ns

Figure 3-17. Configuration from PROGRAMN Timing



1. The CFG pins are normally static (hard wired)

Figure 3-18. Wake-Up Timing

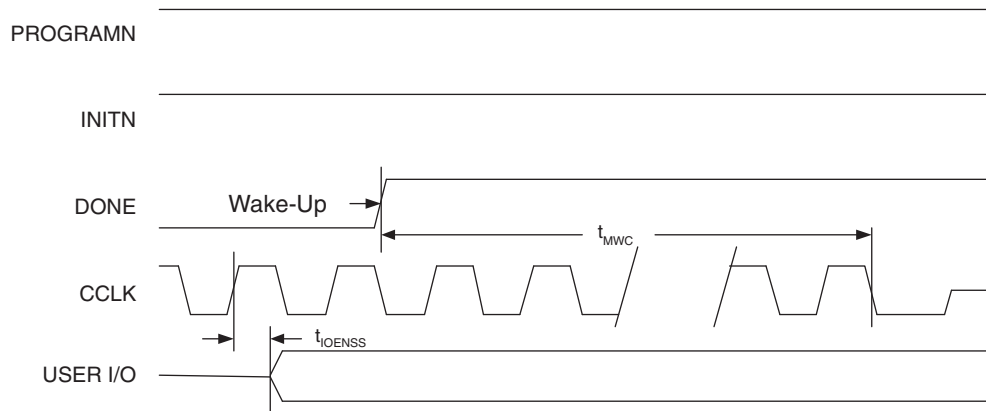
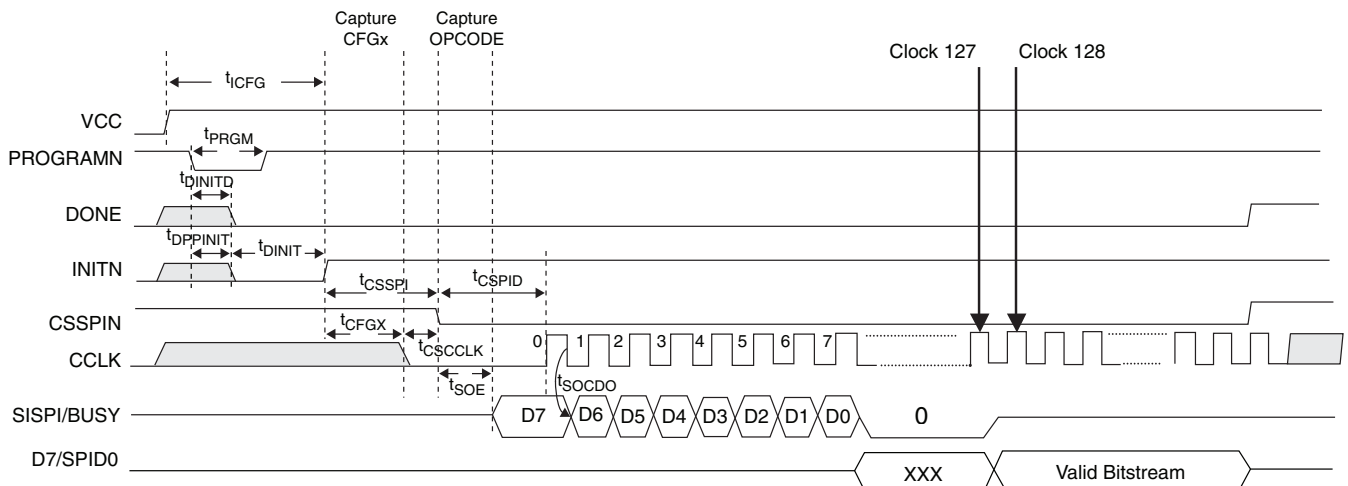


Figure 3-19. sysCONFIG SPI Port Sequence



Signal Descriptions

Signal Name	I/O	Description
General Purpose		
P[Edge] [Row/Column Number*]_[A/B]	I/O	<p>[Edge] indicates the edge of the device on which the pad is located. Valid edge designations are L (Left), B (Bottom), R (Right), T (Top).</p> <p>[Row/Column Number] indicates the PFU row or the column of the device on which the PIC exists. When Edge is T (Top) or (Bottom), only need to specify Row Number. When Edge is L (Left) or R (Right), only need to specify Column Number.</p> <p>[A/B] indicates the PIO within the PIC to which the pad is connected.</p> <p>Some of these user-programmable pins are shared with special function pins. These pin when not used as special purpose pins can be programmed as I/Os for user logic.</p> <p>During configuration the user-programmable I/Os are tri-stated with an internal pull-up resistor enabled. If any pin is not used (or not bonded to a package pin), it is also tri-stated with an internal pull-up resistor enabled after configuration.</p>
GSRN	I	Global RESET signal (active low). Any I/O pin can be GSRN.
NC	—	No connect.
GND	—	Ground. Dedicated pins.
V _{CC}	—	Power supply pins for core logic. Dedicated pins.
V _{CCAUX}	—	Auxiliary power supply pin. It powers all the differential and referenced input buffers. Dedicated pins.
V _{CCIOx}	—	Power supply pins for I/O bank x. Dedicated pins.
V _{REF1_x} , V _{REF2_x}	—	Reference supply pins for I/O bank x. Pre-determined pins in each bank are assigned as V _{REF} inputs. When not used, they may be used as I/O pins.
XRES	—	10K ohm +/-1% resistor must be connected between this pad and ground.
V _{CCPLL}	—	Power supply pin for PLL. Applicable to ECP/EC33 device.
PLL and Clock Functions (Used as user programmable I/O pins when not in use for PLL or clock pins)		
[LOC][num]_PLL[T, C]_IN_A	I	Reference clock (PLL) input pads: ULM, LLM, URM, LRM, num = row from center, T = true and C = complement, index A,B,C...at each side.
[LOC][num]_PLL[T, C]_FB_A	I	Optional feedback (PLL) input pads: ULM, LLM, URM, LRM, num = row from center, T = true and C = complement, index A,B,C...at each side.
PCLK[T, C]_[n:0]_[3:0]	I	Primary Clock pads, T = true and C = complement, n per side, indexed by bank and 0,1,2,3 within bank.
[LOC]DQS[num]	I	DQS input pads: T (Top), R (Right), B (Bottom), L (Left), DQS, num = ball function number. Any pad can be configured to be output.
Test and Programming (Dedicated pins)		
TMS	I	Test Mode Select input, used to control the 1149.1 state machine. Pull-up is enabled during configuration.
TCK	I	Test Clock input pin, used to clock the 1149.1 state machine. No pull-up enabled.

LFEC1, LFEC3, LFEC6/EC6 Logic Signal Connections: 144 TQFP

Pin Number	LFEC1				LFEC3				LFEC6/EC6			
	Pin Function	Bank	LVD S	Dual Function	Pin Function	Bank	LVD S	Dual Function	Pin Function	Bank	LVD S	Dual Function
1	VCCIO7	7			VCCIO7	7			VCCIO7	7		
2	PL2A	7	T	VREF2_7	PL2A	7	T	VREF2_7	PL2A	7	T	VREF2_7
3	PL2B	7	C	VREF1_7	PL2B	7	C	VREF1_7	PL2B	7	C	VREF1_7
4	PL3A	7	T		PL7A	7	T		PL7A	7	T	
5	PL3B	7	C		PL7B	7	C		PL7B	7	C	
6	PL4A	7	T		PL8A	7	T		PL8A	7	T	
7	PL4B	7	C		PL8B	7	C		PL8B	7	C	
8	PL5A	7	T	PCLKT7_0	PL9A	7	T	PCLKT7_0	PL9A	7	T	PCLKT7_0
9	PL5B	7	C	PCLKC7_0	PL9B	7	C	PCLKC7_0	PL9B	7	C	PCLKC7_0
10	XRES	6			XRES	6			XRES	6		
11	NC	-			NC	-			VCC	-		
12	NC	-			NC	-			GND	-		
13	VCC	-			VCC	-			VCC	-		
14	TCK	6			TCK	6			TCK	6		
15	GND	-			GND	-			GND	-		
16	TDI	6			TDI	6			TDI	6		
17	TMS	6			TMS	6			TMS	6		
18	TDO	6			TDO	6			TDO	6		
19	VCCJ	6			VCCJ	6			VCCJ	6		
20	PL7A	6	T	LLM0_PLLT_IN_A	PL11A	6	T	LLM0_PLLT_IN_A	PL20A	6	T	LLM0_PLLT_IN_A
21	PL7B	6	C	LLM0_PLLC_IN_A	PL11B	6	C	LLM0_PLLC_IN_A	PL20B	6	C	LLM0_PLLC_IN_A
22	PL8A	6	T	LLM0_PLLT_FB_A	PL12A	6	T	LLM0_PLLT_FB_A	PL21A	6	T	LLM0_PLLT_FB_A
23	PL8B	6	C	LLM0_PLLC_FB_A	PL12B	6	C	LLM0_PLLC_FB_A	PL21B	6	C	LLM0_PLLC_FB_A
24	VCCIO6	6			VCCIO6	6			VCCIO6	6		
25	PL9A	6	T		PL13A	6	T		PL22A	6	T	
26	PL9B	6	C		PL13B	6	C		PL22B	6	C	
27	PL10A	6	T		PL14A	6	T		PL23A	6	T	
28	GND6	6			GND6	6			GND6	6		
29	PL10B	6	C		PL14B	6	C		PL23B	6	C	
30	PL11A	6	T	LDQS11	PL15A	6	T	LDQS15	PL24A	6	T	LDQS24
31	PL11B	6	C		PL15B	6	C		PL24B	6	C	
32	PL12A	6	T		PL16A	6	T		PL25A	6	T	
33	PL12B	6	C		PL16B	6	C		PL25B	6	C	
34	PL14A	6	T	VREF1_6	PL18A	6	T	VREF1_6	PL27A	6	T	VREF1_6
35	PL14B	6	C	VREF2_6	PL18B	6	C	VREF2_6	PL27B	6	C	VREF2_6
36	VCCIO6	6			VCCIO6	6			VCCIO6	6		
37*	GND5 GND6	-			GND5 GND6	-			GND5 GND6	-		
38	VCCIO5	5			VCCIO5	5			VCCIO5	5		
39	PB2A	5	T		PB10A	5	T		PB10A	5	T	
40	PB2B	5	C		PB10B	5	C		PB10B	5	C	
41	PB3A	5	T		PB11A	5	T		PB11A	5	T	
42	PB3B	5	C		PB11B	5	C		PB11B	5	C	
43	PB5B	5			PB13B	5			PB13B	5		
44	VCCIO5	5			VCCIO5	5			VCCIO5	5		
45	PB6A	5	T	BDQS6	PB14A	5	T	BDQS14	PB14A	5	T	BDQS14
46	PB6B	5	C		PB14B	5	C		PB14B	5	C	
47	PB7A	5	T		PB15A	5	T		PB15A	5	T	
48	PB7B	5	C		PB15B	5	C		PB15B	5	C	
49	PB8A	5	T	VREF2_5	PB16A	5	T	VREF2_5	PB16A	5	T	VREF2_5

LFEC1, LFEC3, LFEC6/EC6 Logic Signal Connections: 144 TQFP (Cont.)

Pin Number	LFEC1				LFEC3				LFEC6/EC6			
	Pin Function	Bank	LVD S	Dual Function	Pin Function	Bank	LVD S	Dual Function	Pin Function	Bank	LVD S	Dual Function
50	PB8B	5	C	VREF1_5	PB16B	5	C	VREF1_5	PB16B	5	C	VREF1_5
51	PB9A	5	T	PCLKT5_0	PB17A	5	T	PCLKT5_0	PB17A	5	T	PCLKT5_0
52	GND5	5			GND5	5			GND5	5		
53	PB9B	5	C	PCLKC5_0	PB17B	5	C	PCLKC5_0	PB17B	5	C	PCLKC5_0
54	VCCAUX	-			VCCAUX	-			VCCAUX	-		
55	VCCIO4	4			VCCIO4	4			VCCIO4	4		
56	PB10A	4	T	WRITEN	PB18A	4	T	WRITEN	PB18A	4	T	WRITEN
57	PB10B	4	C	CS1N	PB18B	4	C	CS1N	PB18B	4	C	CS1N
58	PB11A	4	T	VREF1_4	PB19A	4	T	VREF1_4	PB19A	4	T	VREF1_4
59	PB11B	4	C	CSN	PB19B	4	C	CSN	PB19B	4	C	CSN
60	PB12A	4	T	VREF2_4	PB20A	4	T	VREF2_4	PB20A	4	T	VREF2_4
61	PB12B	4	C	D0/SPID7	PB20B	4	C	D0/SPID7	PB20B	4	C	D0/SPID7
62	PB13A	4	T	D2/SPID5	PB21A	4	T	D2/SPID5	PB21A	4	T	D2/SPID5
63	GND4	4			GND4	4			GND4	4		
64	PB13B	4	C	D1/SPID6	PB21B	4	C	D1/SPID6	PB21B	4	C	D1/SPID6
65	PB14A	4	T	BDQS14	PB22A	4	T	BDQS22	PB22A	4	T	BDQS22
66	PB14B	4	C	D3/SPID4	PB22B	4	C	D3/SPID4	PB22B	4	C	D3/SPID4
67	PB15A	4	T		PB23A	4	T		PB23A	4	T	
68	PB15B	4	C	D4/SPID3	PB23B	4	C	D4/SPID3	PB23B	4	C	D4/SPID3
69	PB16B	4		D5/SPID2	PB24B	4		D5/SPID2	PB24B	4		D5/SPID2
70	PB17B	4		D6/SPID1	PB25B	4		D6/SPID1	PB25B	4		D6/SPID1
71	VCCIO4	4			VCCIO4	4			VCCIO4	4		
72*	GND3 GND4	-			GND3 GND4	-			GND3 GND4	-		
73	VCCIO3	3			VCCIO3	3			VCCIO3	3		
74	PR14A	3		VREF1_3	PR18A	3		VREF1_3	PR27A	3		VREF1_3
75	PR12B	3	C		PR16B	3	C		PR25B	3	C	
76	PR12A	3	T		PR16A	3	T		PR25A	3	T	
77	PR11B	3	C		PR15B	3	C		PR24B	3	C	
78	PR11A	3	T	RDQS11	PR15A	3	T	RDQS15	PR24A	3	T	RDQS24
79	PR10B	3	C	RLM0_PLLC_FB_A	PR14B	3	C	RLM0_PLLC_FB_A	PR23B	3	C	RLM0_PLLC_FB_A
80	GND3	3			GND3	3			GND3	3		
81	PR10A	3	T	RLM0_PLLT_FB_A	PR14A	3	T	RLM0_PLLT_FB_A	PR23A	3	T	RLM0_PLLT_FB_A
82	PR9B	3	C	RLM0_PLLC_IN_A	PR13B	3	C	RLM0_PLLC_IN_A	PR22B	3	C	RLM0_PLLC_IN_A
83	PR9A	3	T	RLM0_PLLT_IN_A	PR13A	3	T	RLM0_PLLT_IN_A	PR22A	3	T	RLM0_PLLT_IN_A
84	VCCIO3	3			VCCIO3	3			VCCIO3	3		
85	PR8B	3	C	DI/CSSPIN	PR12B	3	C	DI/CSSPIN	PR21B	3	C	DI/CSSPIN
86	PR8A	3	T	DOUT/CSON	PR12A	3	T	DOUT/CSON	PR21A	3	T	DOUT/CSON
87	PR7B	3	C	BUSY/SISPI	PR11B	3	C	BUSY/SISPI	PR20B	3	C	BUSY/SISPI
88	PR7A	3	T	D7/SPID0	PR11A	3	T	D7/SPID0	PR20A	3	T	D7/SPID0
89	CFG2	3			CFG2	3			CFG2	3		
90	CFG1	3			CFG1	3			CFG1	3		
91	CFG0	3			CFG0	3			CFG0	3		
92	VCC	-			VCC	-			VCC	-		
93	PROGRAMN	3			PROGRAMN	3			PROGRAMN	3		
94	CCLK	3			CCLK	3			CCLK	3		
95	INITN	3			INITN	3			INITN	3		
96	GND	-			GND	-			GND	-		
97	DONE	3			DONE	3			DONE	3		
98	GND	-			GND	-			GND	-		

LFEC1, LFEC3 Logic Signal Connections: 208 PQFP (Cont.)

Pin Number	LFEC1				LFEC3			
	Pin Function	Bank	LVDS	Dual Function	Pin Function	Bank	LVDS	Dual Function
169	PT13A	1	T		PT21A	1	T	
170	PT12B	1	C		PT20B	1	C	
171	PT12A	1	T		PT20A	1	T	
172	PT11B	1	C	VREF2_1	PT19B	1	C	VREF2_1
173	PT11A	1	T	VREF1_1	PT19A	1	T	VREF1_1
174	PT10B	1	C		PT18B	1	C	
175	PT10A	1	T		PT18A	1	T	
176	VCCIO1	1			VCCIO1	1		
177	VCCAUX	-			VCCAUX	-		
178	PT9B	0	C	PCLKC0_0	PT17B	0	C	PCLKC0_0
179	GND0	0			GND0	0		
180	PT9A	0	T	PCLKT0_0	PT17A	0	T	PCLKT0_0
181	PT8B	0	C	VREF1_0	PT16B	0	C	VREF1_0
182	PT8A	0	T	VREF2_0	PT16A	0	T	VREF2_0
183	PT7B	0	C		PT15B	0	C	
184	PT7A	0	T		PT15A	0	T	
185	PT6B	0	C		PT14B	0	C	
186	PT6A	0	T	TDQS6	PT14A	0	T	TDQS14
187	VCCIO0	0			VCCIO0	0		
188	PT5B	0	C		PT13B	0	C	
189	NC	-			GND0	0		
190	PT5A	0	T		PT13A	0	T	
191	PT4B	0	C		PT12B	0	C	
192	PT4A	0	T		PT12A	0	T	
193	PT3B	0	C		PT11B	0	C	
194	PT3A	0	T		PT11A	0	T	
195	PT2B	0	C		PT10B	0	C	
196	PT2A	0	T		PT10A	0	T	
197	NC	-			VCCIO0	0		
198	NC	-			PT6B	0	C	
199	NC	-			PT6A	0	T	TDQS6
200	NC	-			PT5B	0	C	
201	NC	-			PT5A	0	T	
202	NC	-			PT4B	0	C	
203	NC	-			PT4A	0	T	
204	NC	-			PT3B	0	C	
205	NC	-			PT3A	0	T	
206	NC	-			PT2B	0	C	
207	NC	-			PT2A	0	T	
208	VCCIO0	0			VCCIO0	0		

* Double bonded to the pin.

LFEC6/EC6, LFEC6/EC10 Logic Signal Connections: 208 PQFP (Cont.)

Pin Number	LFEC6/LFEC6				LFEC10/LFEC10			
	Pin Function	Bank	LVDS	Dual Function	Pin Function	Bank	LVDS	Dual Function
169	PT21A	1	T		PT29A	1	T	
170	PT20B	1	C		PT28B	1	C	
171	PT20A	1	T		PT28A	1	T	
172	PT19B	1	C	VREF2_1	PT27B	1	C	VREF2_1
173	PT19A	1	T	VREF1_1	PT27A	1	T	VREF1_1
174	PT18B	1	C		PT26B	1	C	
175	PT18A	1	T		PT26A	1	T	
176	VCCIO1	1			VCCIO1	1		
177	VCCAUX	-			VCCAUX	-		
178	PT17B	0	C	PCLKC0_0	PT25B	0	C	PCLKC0_0
179	GND0	0			GND0	0		
180	PT17A	0	T	PCLKT0_0	PT25A	0	T	PCLKT0_0
181	PT16B	0	C	VREF1_0	PT24B	0	C	VREF1_0
182	PT16A	0	T	VREF2_0	PT24A	0	T	VREF2_0
183	PT15B	0	C		PT23B	0	C	
184	PT15A	0	T		PT23A	0	T	
185	PT14B	0	C		PT22B	0	C	
186	PT14A	0	T	TDQS14	PT22A	0	T	TDQS22
187	VCCIO0	0			VCCIO0	0		
188	PT13B	0	C		PT21B	0	C	
189	GND0	0			GND0	0		
190	PT13A	0	T		PT21A	0	T	
191	PT12B	0	C		PT20B	0	C	
192	PT12A	0	T		PT20A	0	T	
193	PT11B	0	C		PT19B	0	C	
194	PT11A	0	T		PT19A	0	T	
195	PT10B	0	C		PT18B	0	C	
196	PT10A	0	T		PT18A	0	T	
197	VCCIO0	0			VCCIO0	0		
198	PT6B	0	C		PT6B	0	C	
199	PT6A	0	T	TDQS6	PT6A	0	T	TDQS6
200	PT5B	0	C		PT5B	0	C	
201	PT5A	0	T		PT5A	0	T	
202	PT4B	0	C		PT4B	0	C	
203	PT4A	0	T		PT4A	0	T	
204	PT3B	0	C		PT3B	0	C	
205	PT3A	0	T		PT3A	0	T	
206	PT2B	0	C		PT2B	0	C	
207	PT2A	0	T		PT2A	0	T	
208	VCCIO0	0			VCCIO0	0		

*Double bonded to the pin.

LFEC3 and LFEC6/EC6 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFEC3				LFEC6/EC6			
	Ball Function	Bank	LVDS	Dual Function	Ball Function	Bank	LVDS	Dual Function
K2	PL11A	6	T	LLM0_PLLT_IN_A	PL20A	6	T	LLM0_PLLT_IN_A
K1	PL11B	6	C	LLM0_PLLC_IN_A	PL20B	6	C	LLM0_PLLC_IN_A
L2	PL12A	6	T	LLM0_PLLT_FB_A	PL21A	6	T	LLM0_PLLT_FB_A
L1	PL12B	6	C	LLM0_PLLC_FB_A	PL21B	6	C	LLM0_PLLC_FB_A
M2	PL13A	6	T		PL22A	6	T	
M1	PL13B	6	C		PL22B	6	C	
N1	PL14A	6	T		PL23A	6	T	
GND	GND6	6			GND6	6		
N2	PL14B	6	C		PL23B	6	C	
M4	PL15A	6	T	LDQS15	PL24A	6	T	LDQS24
M3	PL15B	6	C		PL24B	6	C	
P1	PL16A	6	T		PL25A	6	T	
R1	PL16B	6	C		PL25B	6	C	
P2	PL17A	6	T		PL26A	6	T	
P3	PL17B	6	C		PL26B	6	C	
N3	PL18A	6	T	VREF1_6	PL27A	6	T	VREF1_6
N4	PL18B	6	C	VREF2_6	PL27B	6	C	VREF2_6
GND	GND6	6			GND6	6		
GND	GND5	5			GND5	5		
P4	PB2A	5	T		PB2A	5	T	
N5	PB2B	5	C		PB2B	5	C	
P5	PB3A	5	T		PB3A	5	T	
P6	PB3B	5	C		PB3B	5	C	
R4	PB4A	5	T		PB4A	5	T	
R3	PB4B	5	C		PB4B	5	C	
T2	PB5A	5	T		PB5A	5	T	
T3	PB5B	5	C		PB5B	5	C	
R5	PB6A	5	T	BDQS6	PB6A	5	T	BDQS6
R6	PB6B	5	C		PB6B	5	C	
T4	PB7A	5	T		PB7A	5	T	
T5	PB7B	5	C		PB7B	5	C	
N6	PB8A	5	T		PB8A	5	T	
M6	PB8B	5	C		PB8B	5	C	
T6	PB9A	5	T		PB9A	5	T	
GND	GND5	5			GND5	5		
T7	PB9B	5	C		PB9B	5	C	
P7	PB10A	5	T		PB10A	5	T	
N7	PB10B	5	C		PB10B	5	C	
R7	PB11A	5	T		PB11A	5	T	
R8	PB11B	5	C		PB11B	5	C	
M7	PB12A	5	T		PB12A	5	T	
M8	PB12B	5	C		PB12B	5	C	
T8	PB13A	5	T		PB13A	5	T	

**LFECP/EC6, LFECP/EC10, LFECP/EC15 Logic Signal Connections:
 484 fpBGA (Cont.)**

LFECP6/LFEC6					LFECP10/LFEC10					LFECP/LFEC15				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
GND	GND5	5			GND	GND5	5			GND	GND5	5		
V7	NC	-			V7	PB2A	5	T		V7	PB2A	5	T	
T6	NC	-			T6	PB2B	5	C		T6	PB2B	5	C	
V8	NC	-			V8	PB3A	5	T		V8	PB3A	5	T	
U7	NC	-			U7	PB3B	5	C		U7	PB3B	5	C	
W5	NC	-			W5	PB4A	5	T		W5	PB4A	5	T	
U6	NC	-			U6	PB4B	5	C		U6	PB4B	5	C	
AA3	NC	-			AA3	PB5A	5	T		AA3	PB5A	5	T	
AB3	NC	-			AB3	PB5B	5	C		AB3	PB5B	5	C	
Y6	NC	-			Y6	PB6A	5	T	BDQS6	Y6	PB6A	5	T	BDQS6
V6	NC	-			V6	PB6B	5	C		V6	PB6B	5	C	
AA5	NC	-			AA5	PB7A	5	T		AA5	PB7A	5	T	
W6	NC	-			W6	PB7B	5	C		W6	PB7B	5	C	
Y5	NC	-			Y5	PB8A	5	T		Y5	PB8A	5	T	
Y4	NC	-			Y4	PB8B	5	C		Y4	PB8B	5	C	
AA4	NC	-			AA4	PB9A	5	T		AA4	PB9A	5	T	
GND	-	-			GND	GND5	5			GND	GND5	5		
AB4	NC	-			AB4	PB9B	5	C		AB4	PB9B	5	C	
Y7	PB2A	5	T		Y7	PB10A	5	T		Y7	PB10A	5	T	
W8	PB2B	5	C		W8	PB10B	5	C		W8	PB10B	5	C	
W7	PB3A	5	T		W7	PB11A	5	T		W7	PB11A	5	T	
U8	PB3B	5	C		U8	PB11B	5	C		U8	PB11B	5	C	
W9	PB4A	5	T		W9	PB12A	5	T		W9	PB12A	5	T	
U9	PB4B	5	C		U9	PB12B	5	C		U9	PB12B	5	C	
Y8	PB5A	5	T		Y8	PB13A	5	T		Y8	PB13A	5	T	
GND	-	-			GND	GND5	5			GND	GND5	5		
Y9	PB5B	5	C		Y9	PB13B	5	C		Y9	PB13B	5	C	
V9	PB6A	5	T	BDQS6	V9	PB14A	5	T	BDQS14	V9	PB14A	5	T	BDQS14
T9	PB6B	5	C		T9	PB14B	5	C		T9	PB14B	5	C	
W10	PB7A	5	T		W10	PB15A	5	T		W10	PB15A	5	T	
U10	PB7B	5	C		U10	PB15B	5	C		U10	PB15B	5	C	
V10	PB8A	5	T		V10	PB16A	5	T		V10	PB16A	5	T	
T10	PB8B	5	C		T10	PB16B	5	C		T10	PB16B	5	C	
AA6	PB9A	5	T		AA6	PB17A	5	T		AA6	PB17A	5	T	
GND	GND5	5			GND	GND5	5			GND	GND5	5		
AB5	PB9B	5	C		AB5	PB17B	5	C		AB5	PB17B	5	C	
AA8	PB10A	5	T		AA8	PB18A	5	T		AA8	PB18A	5	T	
AA7	PB10B	5	C		AA7	PB18B	5	C		AA7	PB18B	5	C	
AB6	PB11A	5	T		AB6	PB19A	5	T		AB6	PB19A	5	T	
AB7	PB11B	5	C		AB7	PB19B	5	C		AB7	PB19B	5	C	
Y10	PB12A	5	T		Y10	PB20A	5	T		Y10	PB20A	5	T	
W11	PB12B	5	C		W11	PB20B	5	C		W11	PB20B	5	C	
AB8	PB13A	5	T		AB8	PB21A	5	T		AB8	PB21A	5	T	
GND	GND5	5			GND	GND5	5			GND	GND5	5		
AB9	PB13B	5	C		AB9	PB21B	5	C		AB9	PB21B	5	C	
AA10	PB14A	5	T	BDQS14	AA10	PB22A	5	T	BDQS22	AA10	PB22A	5	T	BDQS22
AA9	PB14B	5	C		AA9	PB22B	5	C		AA9	PB22B	5	C	
Y11	PB15A	5	T		Y11	PB23A	5	T		Y11	PB23A	5	T	
AA11	PB15B	5	C		AA11	PB23B	5	C		AA11	PB23B	5	C	
V11	PB16A	5	T	VREF2_5	V11	PB24A	5	T	VREF2_5	V11	PB24A	5	T	VREF2_5

LFEC20/EC20 and LFEC20/EC33 Logic Signal Connections: 484 fpBGA (Cont.)

LFEC20/LFEC20					LFEC20/LFEC33				
Ball Number	Ball Function	Bank	LVD S	Dual Function	Ball Number	Ball Function	Bank	LVD S	Dual Function
U9	PB20B	5	C		U9	PB20B	5	C	
Y8	PB21A	5	T		Y8	PB21A	5	T	
GND	GND5	5			GND	GND5	5		
Y9	PB21B	5	C		Y9	PB21B	5	C	
V9	PB22A	5	T	BDQS22	V9	PB22A	5	T	BDQS22
T9	PB22B	5	C		T9	PB22B	5	C	
W10	PB23A	5	T		W10	PB23A	5	T	
U10	PB23B	5	C		U10	PB23B	5	C	
V10	PB24A	5	T		V10	PB24A	5	T	
T10	PB24B	5	C		T10	PB24B	5	C	
AA6	PB25A	5	T		AA6	PB25A	5	T	
GND	GND5	5			GND	GND5	5		
AB5	PB25B	5	C		AB5	PB25B	5	C	
AA8	PB26A	5	T		AA8	PB26A	5	T	
AA7	PB26B	5	C		AA7	PB26B	5	C	
AB6	PB27A	5	T		AB6	PB27A	5	T	
AB7	PB27B	5	C		AB7	PB27B	5	C	
Y10	PB28A	5	T		Y10	PB28A	5	T	
W11	PB28B	5	C		W11	PB28B	5	C	
AB8	PB29A	5	T		AB8	PB29A	5	T	
GND	GND5	5			GND	GND5	5		
AB9	PB29B	5	C		AB9	PB29B	5	C	
AA10	PB30A	5	T	BDQS30	AA10	PB30A	5	T	BDQS30
AA9	PB30B	5	C		AA9	PB30B	5	C	
Y11	PB31A	5	T		Y11	PB31A	5	T	
AA11	PB31B	5	C		AA11	PB31B	5	C	
V11	PB32A	5	T	VREF2_5	V11	PB32A	5	T	VREF2_5
V12	PB32B	5	C	VREF1_5	V12	PB32B	5	C	VREF1_5
AB10	PB33A	5	T	PCLKT5_0	AB10	PB33A	5	T	PCLKT5_0
GND	GND5	5			GND	GND5	5		
AB11	PB33B	5	C	PCLKC5_0	AB11	PB33B	5	C	PCLKC5_0
Y12	PB34A	4	T	WRITEN	Y12	PB34A	4	T	WRITEN
U11	PB34B	4	C	CS1N	U11	PB34B	4	C	CS1N
W12	PB35A	4	T	VREF1_4	W12	PB35A	4	T	VREF1_4
U12	PB35B	4	C	CSN	U12	PB35B	4	C	CSN
W13	PB36A	4	T	VREF2_4	W13	PB36A	4	T	VREF2_4
U13	PB36B	4	C	D0/SPID7	U13	PB36B	4	C	D0/SPID7
AA12	PB37A	4	T	D2/SPID5	AA12	PB37A	4	T	D2/SPID5
GND	GND4	4			GND	GND4	4		
AB12	PB37B	4	C	D1/SPID6	AB12	PB37B	4	C	D1/SPID6
T13	PB38A	4	T	BDQS38	T13	PB38A	4	T	BDQS38
V13	PB38B	4	C	D3/SPID4	V13	PB38B	4	C	D3/SPID4
W14	PB39A	4	T		W14	PB39A	4	T	
U14	PB39B	4	C	D4/SPID3	U14	PB39B	4	C	D4/SPID3

LFCEP/EC20, LFCEP/EC33 Logic Signal Connections: 672 fpBGA (Cont.)

LFCEP/EC20					LFCEP/EC33				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
Y6	NC	-			Y6	PL62A	6	T	
W7	NC	-			W7	PL62B	6	C	
AA4	NC	-			AA4	PL63A	6	T	
AB3	NC	-			AB3	PL63B	6	C	
AC2	NC	-			AC2	PL64A	6	T	
-	-	-			GND	GND6	6		
AC3	NC	-			AC3	PL64B	6	C	
AA5	NC	-			AA5	PL65A	6	T	LDQS65
AB5	NC	-			AB5	PL65B	6	C	
AD3	NC	-			AD3	PL66A	6	T	
AD2	NC	-			AD2	PL66B	6	C	
AE1	NC	-			AE1	PL67A	6	T	
AD1	NC	-			AD1	PL67B	6	C	
AB4	PL48A	6	T	VREF1_6	AB4	PL68A	6	T	VREF1_6
AC4	PL48B	6	C	VREF2_6	AC4	PL68B	6	C	VREF2_6
GND	GND6	6			GND	GND6	6		
GND	GND5	5			GND	GND5	5		
AB6	PB2A	5	T		AB6	PB2A	5	T	
AA6	PB2B	5	C		AA6	PB2B	5	C	
AC7	PB3A	5	T		AC7	PB3A	5	T	
Y8	PB3B	5	C		Y8	PB3B	5	C	
AB7	PB4A	5	T		AB7	PB4A	5	T	
AA7	PB4B	5	C		AA7	PB4B	5	C	
AC6	PB5A	5	T		AC6	PB5A	5	T	
AC5	PB5B	5	C		AC5	PB5B	5	C	
AB8	PB6A	5	T	BDQS6	AB8	PB6A	5	T	BDQS6
AC8	PB6B	5	C		AC8	PB6B	5	C	
AE2	PB7A	5	T		AE2	PB7A	5	T	
AA8	PB7B	5	C		AA8	PB7B	5	C	
AF2	PB8A	5	T		AF2	PB8A	5	T	
Y9	PB8B	5	C		Y9	PB8B	5	C	
AD5	PB9A	5	T		AD5	PB9A	5	T	
GND	GND5	5			GND	GND5	5		
AD4	PB9B	5	C		AD4	PB9B	5	C	
AD8	PB10A	5	T		AD8	PB10A	5	T	
AC9	PB10B	5	C		AC9	PB10B	5	C	
AE3	PB11A	5	T		AE3	PB11A	5	T	
AB9	PB11B	5	C		AB9	PB11B	5	C	
AF3	PB12A	5	T		AF3	PB12A	5	T	
AD9	PB12B	5	C		AD9	PB12B	5	C	
AE4	PB13A	5	T		AE4	PB13A	5	T	
GND	GND5	5			GND	GND5	5		

Thermal Management

Thermal management is recommended as part of any sound FPGA design methodology. To assess the thermal characteristics of a system, Lattice specifies a maximum allowable junction temperature in all device data sheets. Designers must complete a thermal analysis of their specific design to ensure that the device and package do not exceed the junction temperature limits. Refer to the Thermal Management document to find the device/package specific thermal values.

For Further Information

For further information regarding Thermal Management, refer to the following located on the Lattice website at www.latticesemi.com.

- Thermal Management document
- Technical Note TN1052 - Power Estimation and Management for LatticeECP/EC and LatticeXP Devices
- Power Calculator tool included with Lattice's ispLEVER design tool, or as a standalone download from www.latticesemi.com/software

Conventional Packaging
LatticeEC Commercial

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFEC1E-3Q208C	112	-3	PQFP	208	COM	1.5K
LFEC1E-4Q208C	112	-4	PQFP	208	COM	1.5K
LFEC1E-5Q208C	112	-5	PQFP	208	COM	1.5K
LFEC1E-3T144C	97	-3	TQFP	144	COM	1.5K
LFEC1E-4T144C	97	-4	TQFP	144	COM	1.5K
LFEC1E-5T144C	97	-5	TQFP	144	COM	1.5K
LFEC1E-3T100C	67	-3	TQFP	100	COM	1.5K
LFEC1E-4T100C	67	-4	TQFP	100	COM	1.5K
LFEC1E-5T100C	67	-5	TQFP	100	COM	1.5K

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFEC3E-3F256C	160	-3	fpBGA	256	COM	3.1K
LFEC3E-4F256C	160	-4	fpBGA	256	COM	3.1K
LFEC3E-5F256C	160	-5	fpBGA	256	COM	3.1K
LFEC3E-3Q208C	145	-3	PQFP	208	COM	3.1K
LFEC3E-4Q208C	145	-4	PQFP	208	COM	3.1K
LFEC3E-5Q208C	145	-5	PQFP	208	COM	3.1K
LFEC3E-3T144C	97	-3	TQFP	144	COM	3.1K
LFEC3E-4T144C	97	-4	TQFP	144	COM	3.1K
LFEC3E-5T144C	97	-5	TQFP	144	COM	3.1K
LFEC3E-3T100C	67	-3	TQFP	100	COM	3.1K
LFEC3E-4T100C	67	-4	TQFP	100	COM	3.1K
LFEC3E-5T100C	67	-5	TQFP	100	COM	3.1K

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFEC6E-3F484C	224	-3	fpBGA	484	COM	6.1K
LFEC6E-4F484C	224	-4	fpBGA	484	COM	6.1K
LFEC6E-5F484C	224	-5	fpBGA	484	COM	6.1K
LFEC6E-3F256C	195	-3	fpBGA	256	COM	6.1K
LFEC6E-4F256C	195	-4	fpBGA	256	COM	6.1K
LFEC6E-5F256C	195	-5	fpBGA	256	COM	6.1K
LFEC6E-3Q208C	147	-3	PQFP	208	COM	6.1K
LFEC6E-4Q208C	147	-4	PQFP	208	COM	6.1K
LFEC6E-5Q208C	147	-5	PQFP	208	COM	6.1K
LFEC6E-3T144C	97	-3	TQFP	144	COM	6.1K
LFEC6E-4T144C	97	-4	TQFP	144	COM	6.1K
LFEC6E-5T144C	97	-5	TQFP	144	COM	6.1K

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFEC10E-3F484C	288	-3	fpBGA	484	COM	10.2K
LFEC10E-4F484C	288	-4	fpBGA	484	COM	10.2K
LFEC10E-5F484C	288	-5	fpBGA	484	COM	10.2K
LFEC10E-3F256C	195	-3	fpBGA	256	COM	10.2K